



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

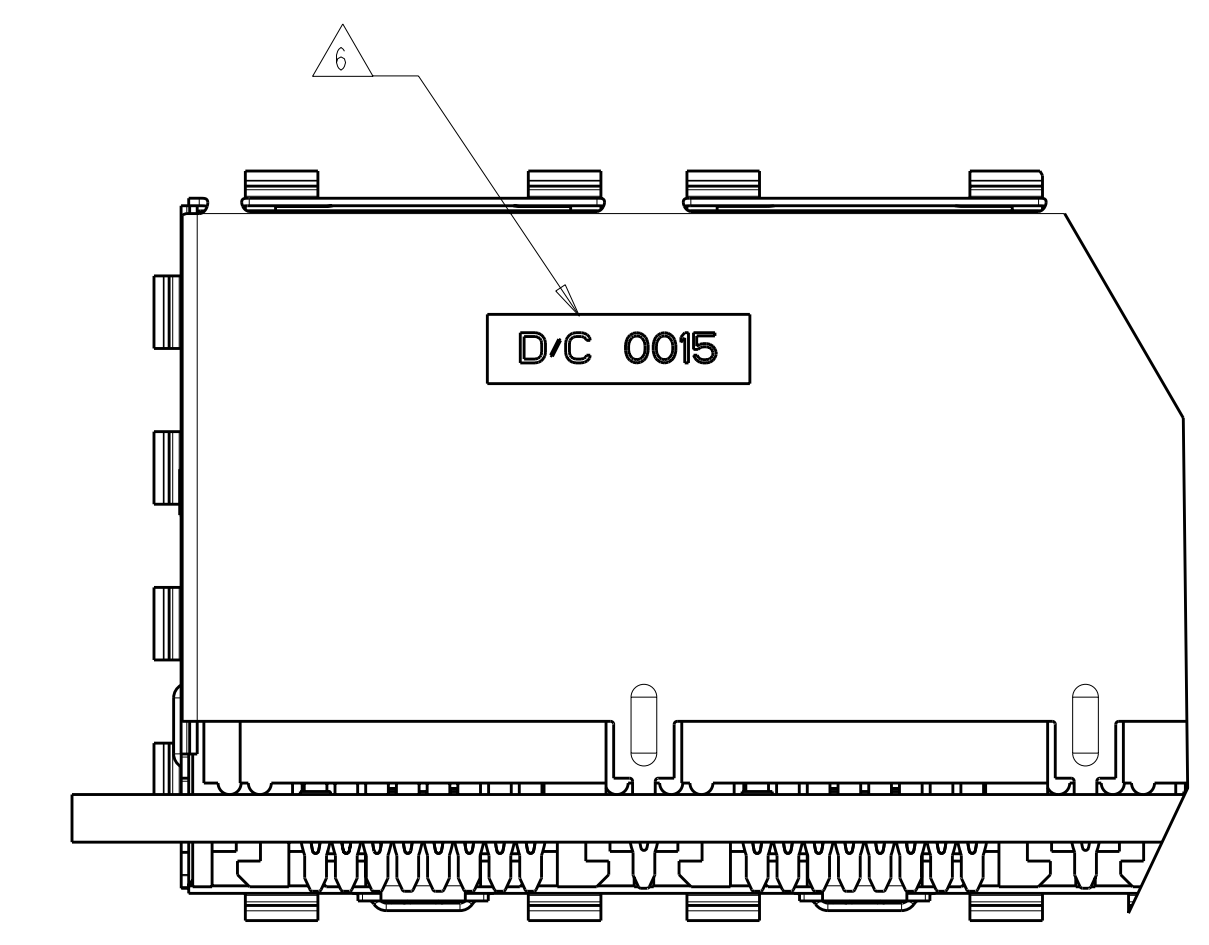
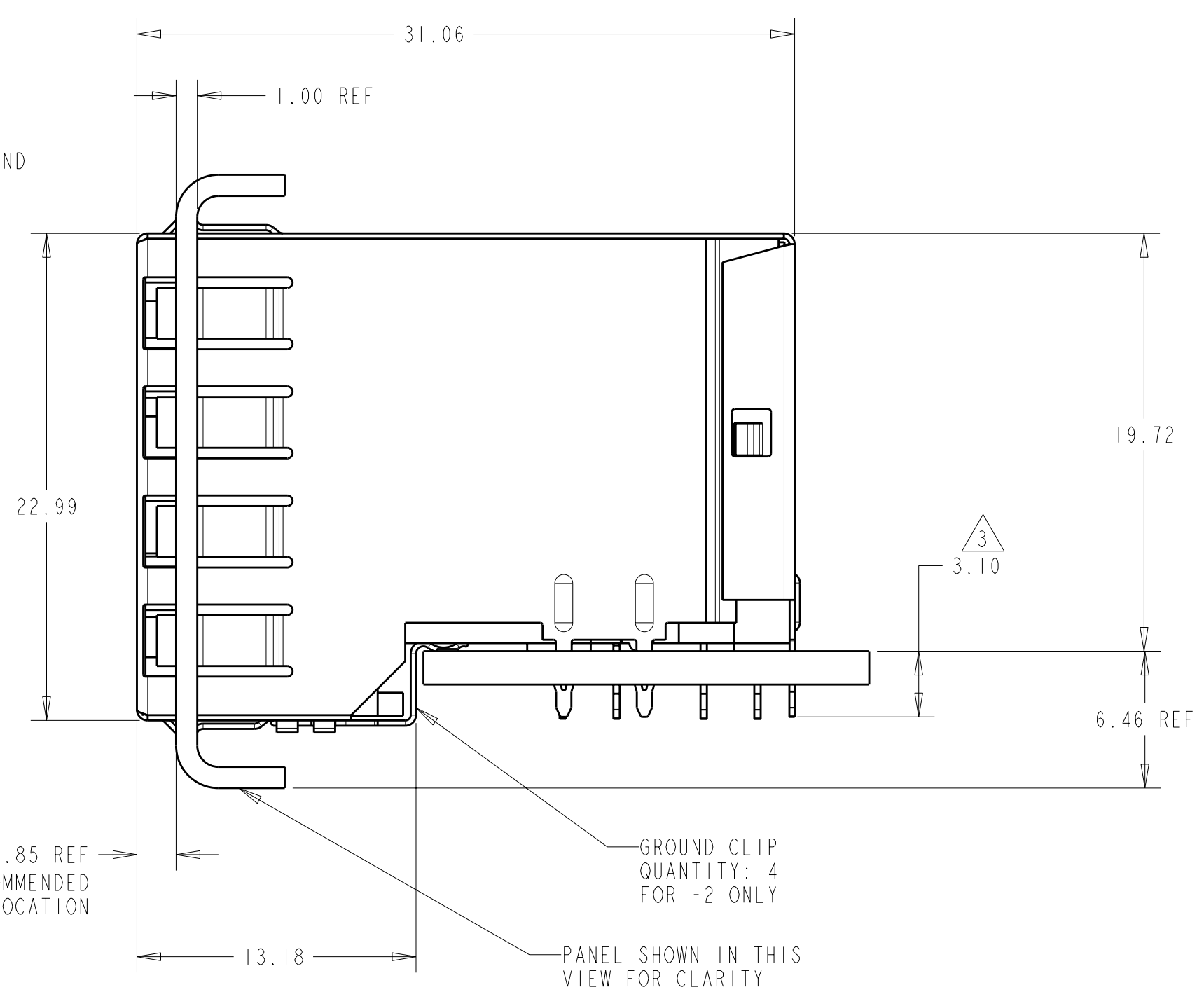
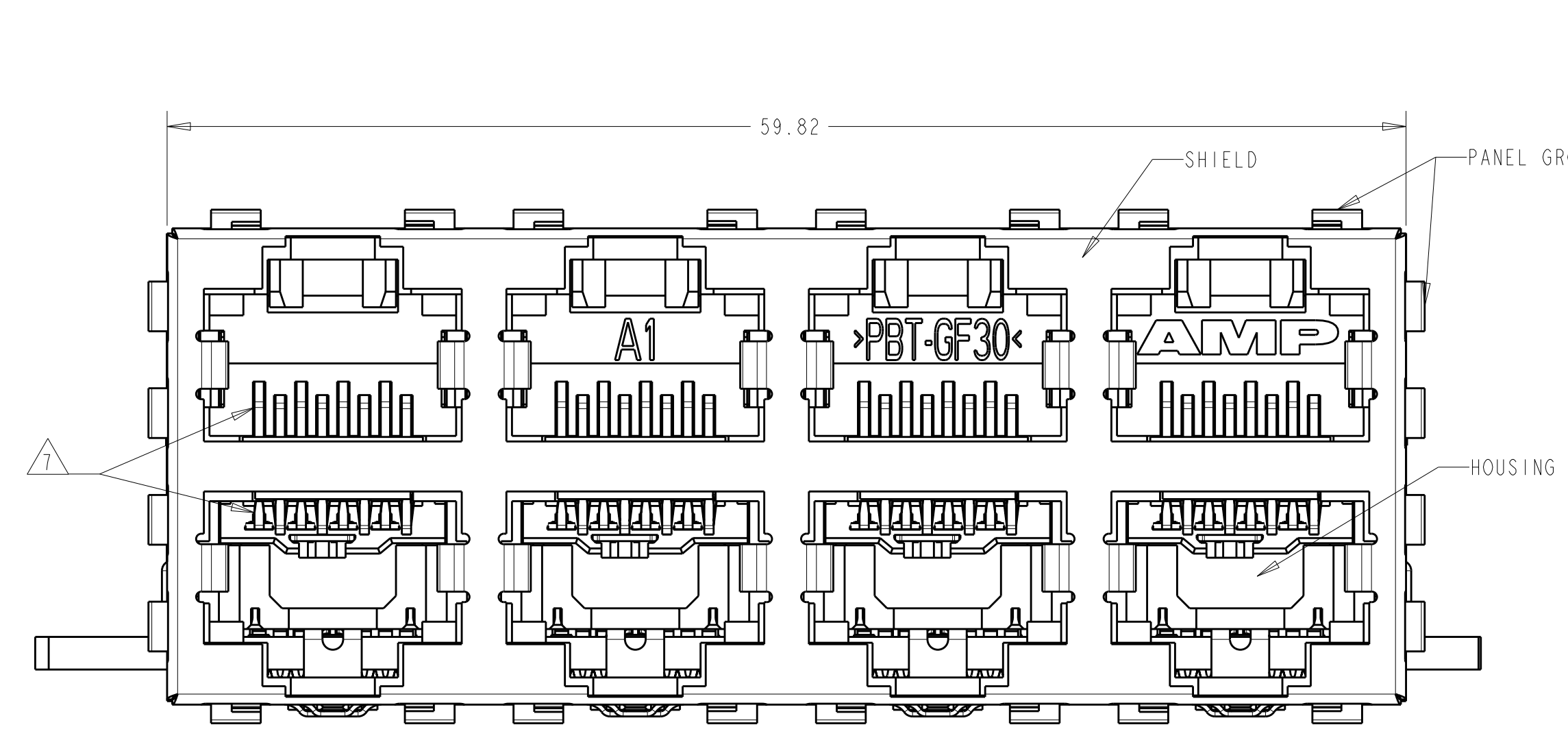
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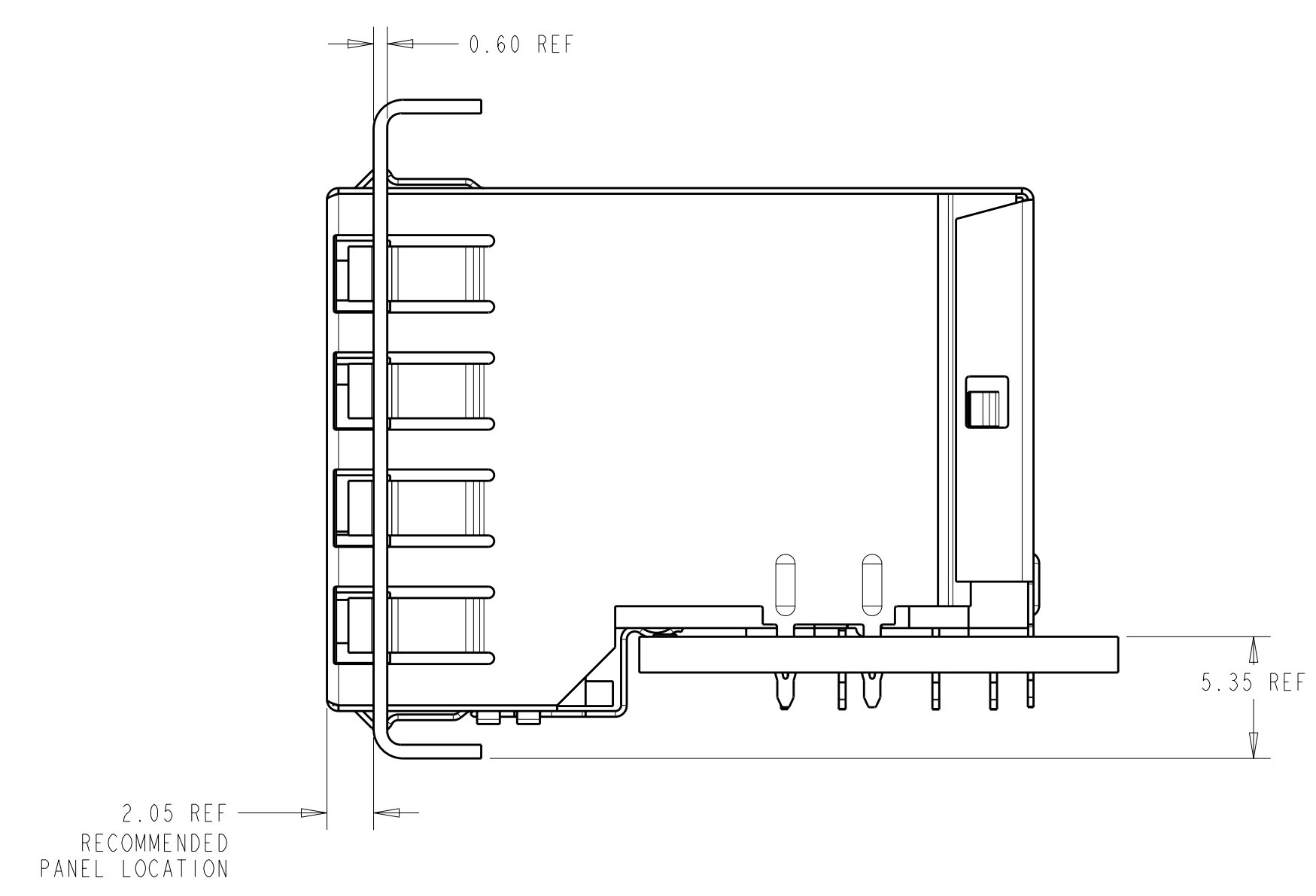
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



| LOC | DIST | REV           | DATE      | BY  | APP'D |
|-----|------|---------------|-----------|-----|-------|
| AA  | 00   |               |           |     |       |
| A   |      | RELEASED      | 21OCT2006 | LAM | JW    |
| B   |      | ECO-07-001858 | 29JAN2007 | LAM | JW    |
| C   |      | ECO-07-008800 | 18APR2007 | LAM | JW    |
| D   |      | ECR-08-019486 | 04AUG2008 | A.L | S.Y   |



**ATCA PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT**



**AMC PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT**

- MATERIAL:  
 HOUSING: PBT POLYESTER, BLACK, UL 94V-0  
 TERMINALS: 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 2.0µm MINIMUM THICK MATTE TIN IN COMPLIANT PIN TERMINAL AREA OVER 1.27µm MINIMUM THICK NICKEL UNDERPLATE  
 SHIELD: 0.25 THICK COPPER ALLOY PLATED WITH 2.03µm MINIMUM TIN OVER 1.27 µm MINIMUM NICKEL  
 GROUND CLIP: 0.25 THICK COPPER ALLOY PRE-PLATED WITH 2.03µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 MAXIMUM PIN LENGTH 3.40 FROM TOP SURFACE OF PC BOARD  
 4 FINISHED PLATED THROUGH HOLE DIAMETER - ANNULAR RING DIAMETER 1.3 TO 1.5  
 5 DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER  
 6 DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN  
 7 CONTACTS ARE NOT INTENDED TO BE ALIGNED WITH EACH OTHER

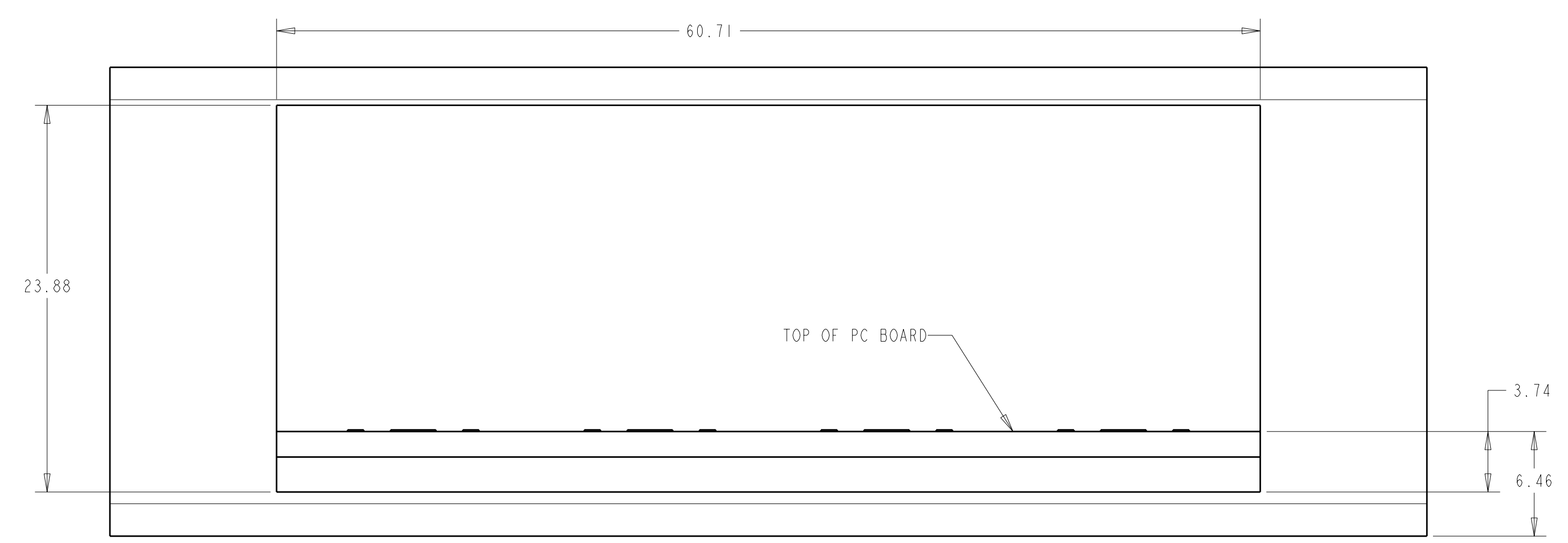
| M DIM | DESCRIPTION         | PART NUMBER       |
|-------|---------------------|-------------------|
| 15.88 | WITH GROUND CLIP    | 1888506-2 (SHOWN) |
| 16.13 | WITHOUT GROUND CLIP | 1888506-1         |

|  |  |   |  |  |  |
|--|--|---|--|--|--|
| DIMENSIONS: mm<br>TOLERANCES UNLESS OTHERWISE SPECIFIED:<br>9 PLC ±<br>1 PLC ±0.13<br>5 PLC ±<br>4 PLC ±<br>ANGLES ±1°<br>FINISH - |  | DWN L.A.MAYER 21OCT2006<br>CHK J.WESTMAN 21OCT2006<br>APVD S.FLICKINGER 21OCT2006<br>PRODUCT SPEC 108-1854<br>APPLICATION SPEC 114-2160<br>WEIGHT -<br>CUSTOMER DRAWING |  | Tyco Electronics Corporation<br>Harrisburg, PA 17105-3608<br>NAME STACKED MOD JACK ASSEMBLY, 2 X 4, 8 POSN, RJ45, SHIELDED, PANEL GROUND, OFFSET, CAT 5<br>SIZE CAGE CODE DRAWING NO RESTRICTED TO A 00779 C-1888506<br>SCALE 4:1 SHEET 1 OF 2 REV D |  |
|--|--|---|--|--|--|

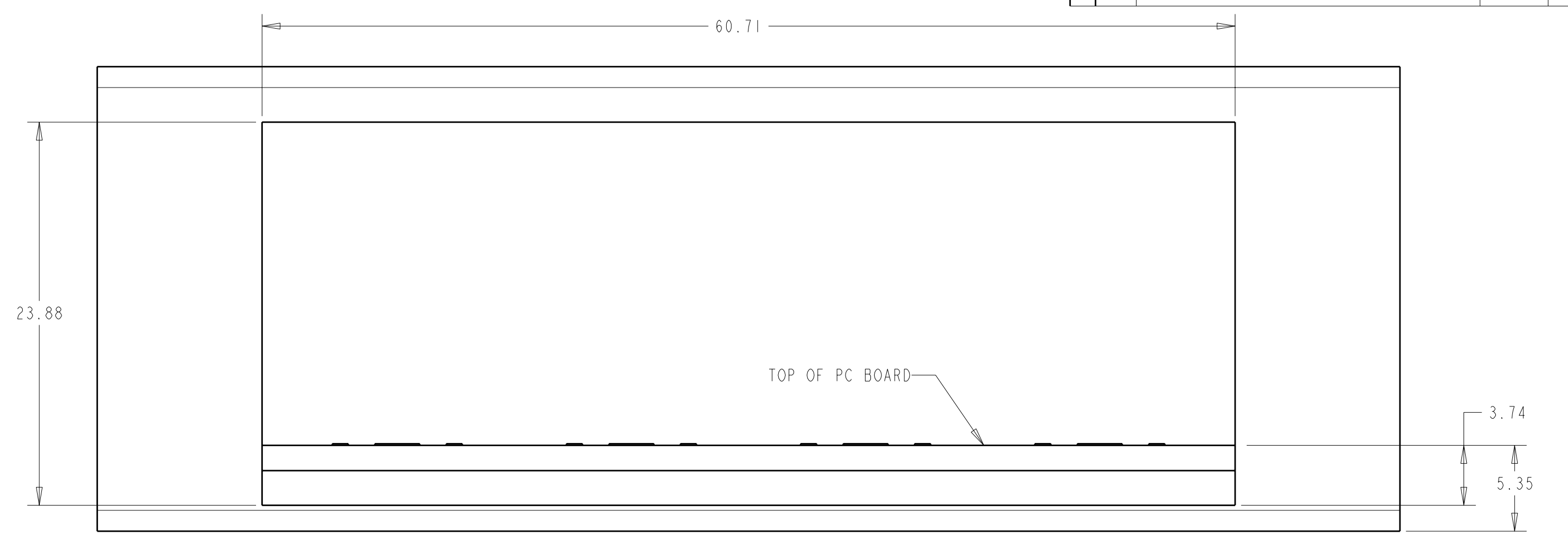
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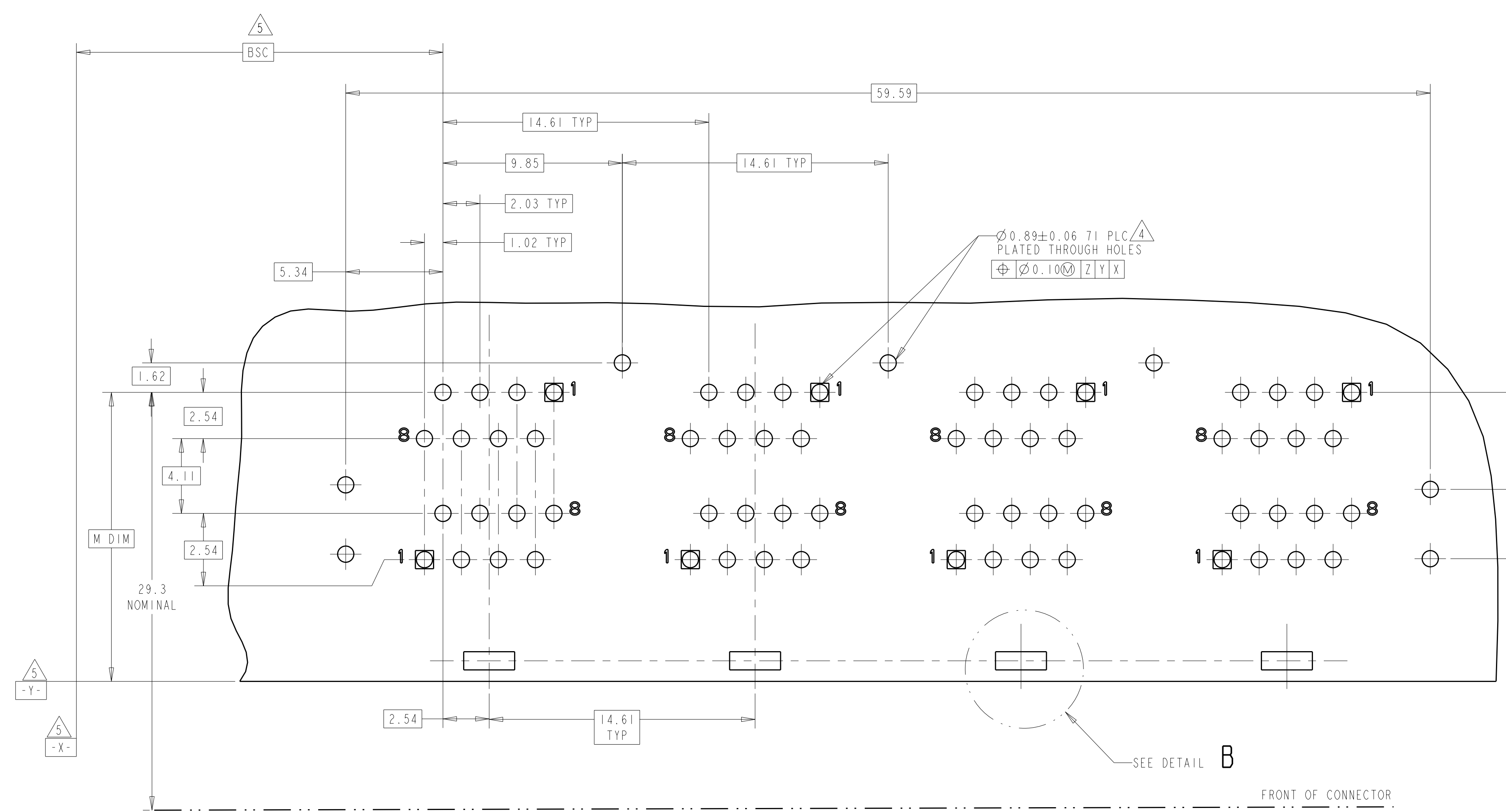
| REVISIONS |      |    |      |
|-----------|------|----|------|
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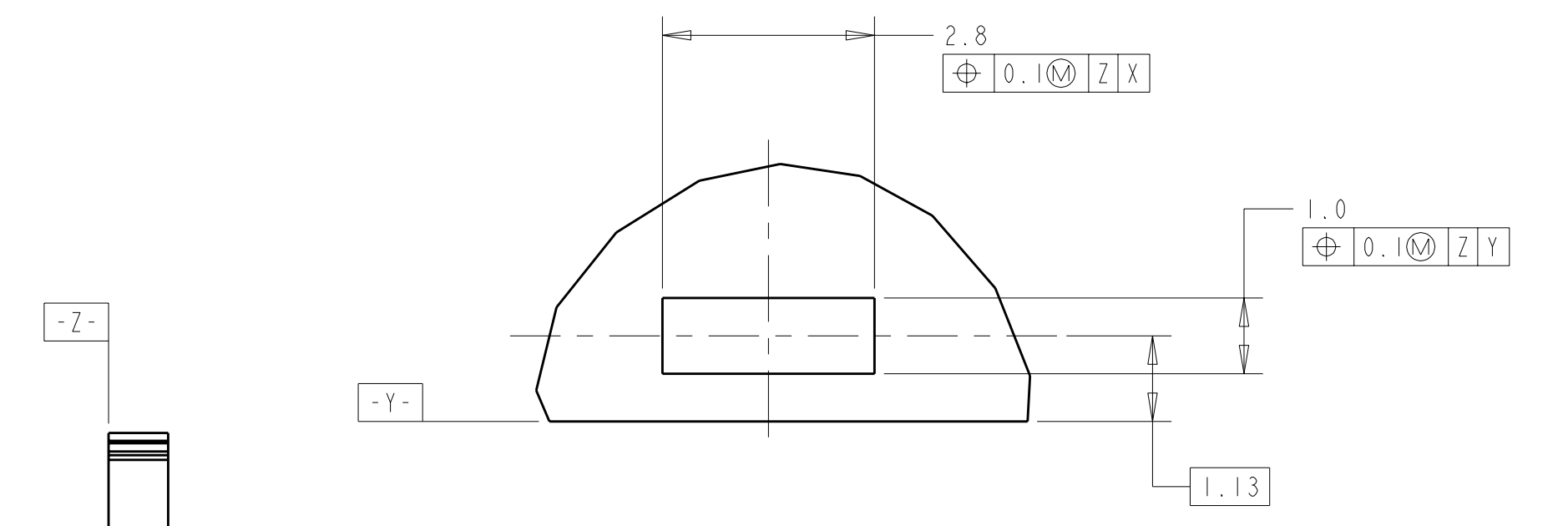
ATCA PANEL AND  
PRINTED CIRCUIT BOARD LAYOUT



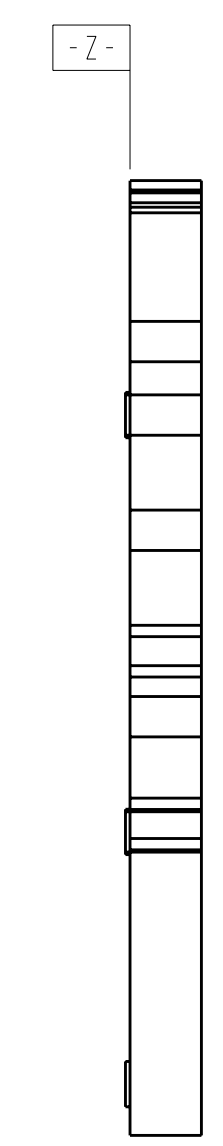
AMC PANEL AND  
PRINTED CIRCUIT BOARD LAYOUT



PC BOARD LAYOUT  
(COMPONENT SIDE)



DETAIL B  
SCALE 12:1  
PLATED PADS REQUIRED FOR  
1888506-2 (PRODUCT WITH  
GROUNDING CLIP)  
4 PLC



|                       |  |  |  |   |  |  |  |
|-----------------------|--|--|--|---|--|--|--|
| DIMENSIONS:<br>mm<br> |  | TOLERANCES UNLESS OTHERWISE SPECIFIED:<br>9 PLC ±<br>1 PLC ±0.13<br>5 PLC ±<br>4 PLC ±<br>ANGLES ±1°<br>FINISH - |  | DWN L.A.MAYER 21OCT2006<br>CHK J.WESTMAN 21OCT2006<br>APVD S.FLICKINGER 21OCT2006<br>PRODUCT SPEC 108-1854<br>APPLICATION SPEC 114-2160<br>WEIGHT -<br>CUSTOMER DRAWING |  | Tyco Electronics<br>Tyco Electronics Corporation<br>Harrisburg, PA 17105-3608<br>NAME STACKED MOD JACK ASSEMBLY, 2 X 4,<br>8 POSN, RJ45, SHIELDED, PANEL<br>GROUND, OFFSET, CAT 5<br>SIZE CAGE CODE DRAWING NO RESTRICTED TO<br>A1100779 C=1888506 -<br>SCALE 1:1 SHEET 2 OF 2 REV D |  |
|-----------------------|--|--|--|---|--|--|--|